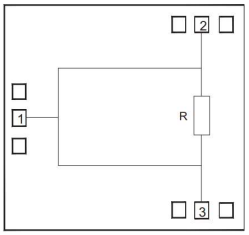
Performance

- Frequency: 1~2GHz
- Insertion loss: 0.7dB
- Chip size: 1.10*1.10*0.1mm

Function Diagram

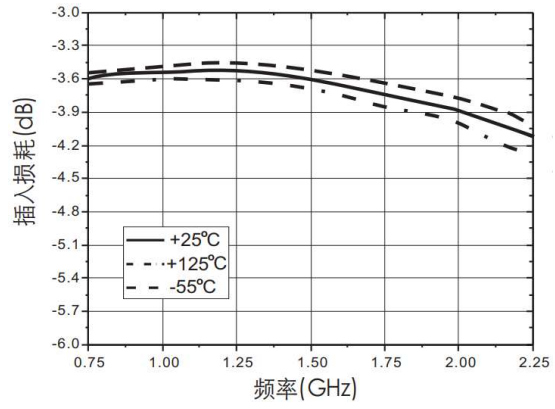


Electrical Specifications (Ta=+25℃, 50Ω system)

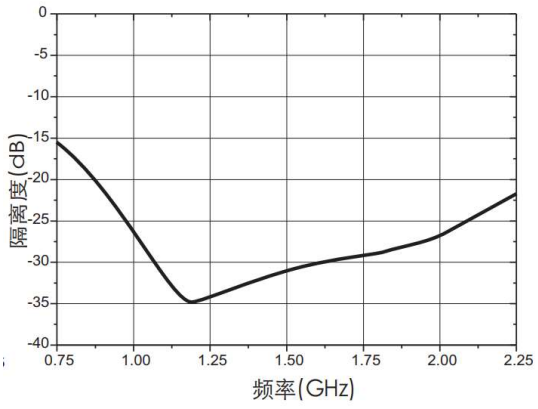
Parameter	Min	Typical	Max	Unit
Frequency Range		1~2		GHz
Insertion Loss	-	0.7	1.0	dB
Insertion Loss Ripple	-	±0.3	-	dB
Isolation	25	30	-	dB
VSWRin	15	20	-	dB
VSWRout	16	20	-	dB

Test Curves

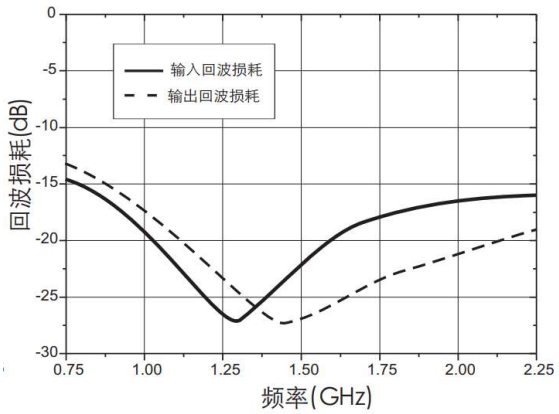
Insertion loss vs. Freq



Isolation vs. Freq



Input/Output Return Loss vs. Freq

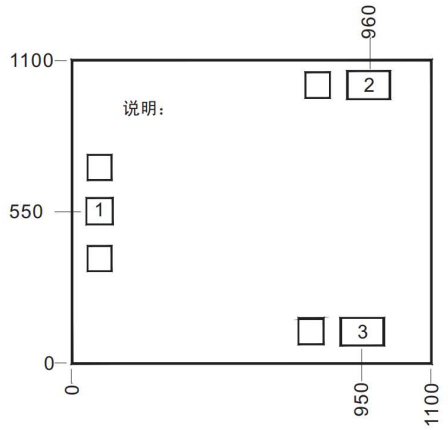


Absolute Max Ratings

RF Input Power	+37dBm
Storage Temperature	-65~150℃
Operating Temperature	-55~125℃
Junction Temperature	175℃
Static Protection (HBM)	Class 1A

ELECTROSTATIC SENSITIVE DEVICE
OBSERVE HANDLING PRECAUTIONS

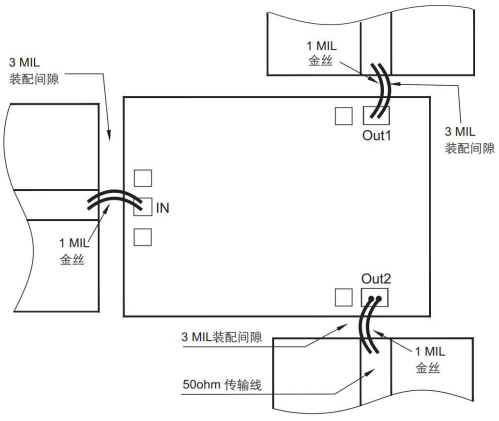
Outline Size



Note:

1. Unit: um
2. Bottom side is gold plated
3. Bottom side is GND
4. Bonding pads is gold plated
   Pads size: 1, 100*100 um； 2, 3： 200*100 um
5. Don't bonding on thru holds
6. Tolerance: ±50um

Assembly Diagram



Bonding Definition

No.	Symbol	Description
1	In	RF Input, 50ohm
2, 3	Out1, Out2	RF Output, 50ohm
	GND	Bottom must be grounded